

VD66GY promodules: Camera module evaluation samples for instant integration of VD66GY sensor



Order code	Description
CAM-6GY-073VIS	VD66GY promodule with 73° FoV lens
CAM-6GY-084VIS	VD66GY promodule with 84° FoV lens
CAM-6GY-152VIS	VD66GY promodule with 152° FoV lens

Features

- “Promodules”: turnkey camera modules for evaluation:
 - Including **VD66GY** image sensor, lens holder, lens, and plug-and-play flex connection.
 - Lens focused, glued, and tested in a cleanroom environment using specialized equipment.
 - Small footprint down to 6.5 mm square.
- Various lens options:
 - Ultra-wide-angle lens for wide scene capture (152° DFOV).
 - Highly compact lens for a thin module (84° DFOV).
 - General-purpose lens enabling various system setups (73° DFOV).
- Plug-and-play connector to change promodules at any time:
 - FPC-to-board 30-pin connector.
 - Same connector for all ST promodules.
- Ready for evaluation and integration:
 - On a computer with a USB output using the **EVK Main hardware tool** and the **Evaluation GUI** free software.
 - On embedded processing platforms with a MIPI CSI-2 output using the **P-Board** hardware tool and free **Linux software tools**.
- Promodules are also available in monochrome versions (CAM-56G3).

Description

The CAM-66GY promodules are a full range of sample camera modules made for a seamless evaluation and integration of the VD66GY 1.5-megapixel color image sensor. These ready-to-use vision extensions integrate VD66GY image sensor, lens holder, lens, and plug-and-play flex connection in a tiny format down to 6.5 mm square.

The CAM-66GY line leverages the complete toolbox of on-chip features of the VD66GY image sensor embedded, such as binning, autoexposure, or context management. Multiple GPIOs enable users to synchronize the modules with triggers and illumination. Featuring MIPI CSI-2 output, the promodules are perfectly suited for embedded low-power setups.

Multiple promodule references are available, featuring various lenses to best match the needs of every application in terms of optical setup and mechanical constraints. All camera modules are equipped with the same FPC-to-board connector and pinout. This plug-and-play architecture allows users to change promodule instantly, and reuse the same setup with different lenses, color options, and even different image sensors in the STMicroelectronics portfolio.

CAM-66GY promodules can be tested and integrated on computers or embedded processing boards using hardware and software tools from ST BrightSense. The compatible **EVK Main** and **P-Board** hardware kits enable straight connection to PC and embedded processing platforms respectively. Evaluation GUI software and Linux drivers are available for download from the **Imaging Software** section of the website.

Figure 1. Common connector to all ST promodules

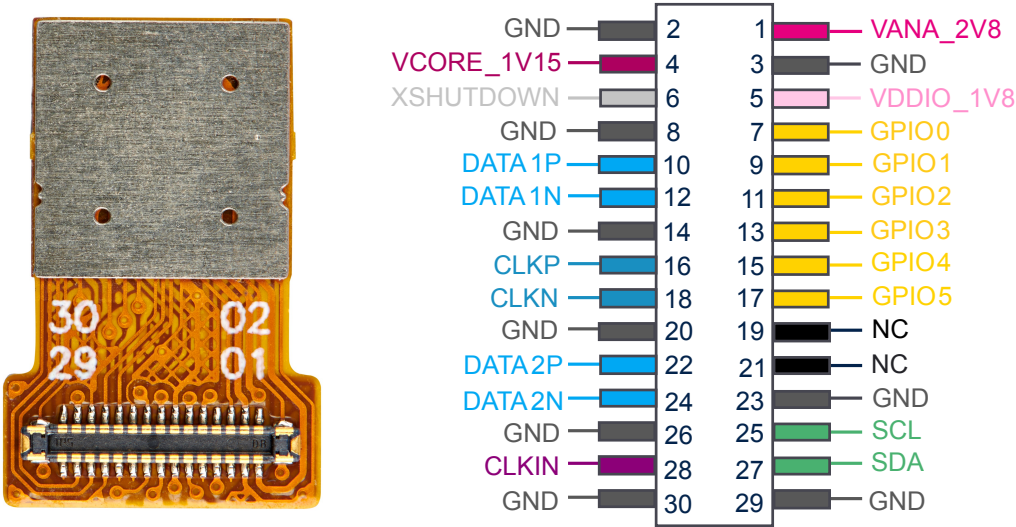


Table 1. Evaluation & development setup with CAM-66GY promodules

<p>Setup for embedded platforms with MIPI CSI-2 output</p> <p>CAM-66GY promodule + P-Board</p>	<p>Setup for computer with USB output</p> <p>CAM-66GY promodule + EVK Main</p>

1 Technical specifications

Table 2. Technical specifications

Category	Parameter	Common specifications		
Image characteristics	Sensor featured	VD66GY		
	Resolution	1.53 MP – 1124 x 1364		
	Aspect ratio	5 : 6		
	Shutter type	Global shutter		
	Color option	Color RGB		
Electrical characteristics	Connector type	FPC-to-board		
	Connector reference	Hirose BM28 B0.6-30DP/2-0.35V		
	Pinout	30 pins		
	Output interface	MIPI CSI-2 1 or 2 lanes		
	Control interface	I ² C		
	Output format	RAW8, RAW10		
	Supply voltages	2.8 V – 1.8 V – 1.15 V		
	External clock frequency	6 to 27 MHz		
Embedded features	Image quality optimization	<ul style="list-style-type: none"> • Autoexposure • Automatic dark calibration • Defective pixel correction • Analog and digital gains 		
	Power and data optimization	<ul style="list-style-type: none"> • Cropping • Binning • Subsampling • Context management with up to 4 contexts 		
	Others	<ul style="list-style-type: none"> • Mirror/Flip • Test pattern generation • Temperature sensor • GPIOs x6 		
Category	Parameter	CAM-6GY-073VIS	CAM-6GY-084VIS	CAM-6GY-152VIS
Optical characteristics	Aperture – f/#	F/2.2	F/2.0	F/2.0
	Field of view – D H V	73° 51° 60°	84° 60° 69°	152° 97° 118°
	EFL	3.03 mm	2.51 mm	1.69 mm
	Depth of field	43 cm -> ∞	30 cm -> 6 m	14.4 cm -> ∞
	TV distortion	< 1 %	< 1.5 %	< 27 %
	Filter	Visible	Visible	Visible
Mechanical characteristics	Module head dimension – L x W x H	6.5 x 6.5 x 4.68 mm	6.5 x 6.5 x 3.98 mm	9.0 x 9.0 x 7.15 mm
	Module total dimension – L x W x H	12.4 x 8.0 x 4.68 mm	12.4 x 8.0 x 3.98 mm	13.65 x 9.0 x 7.15 mm
	Distance from connector to optical center	7.45 mm	7.45 mm	7.45 mm

Revision history

Table 3. Document revision history

Date	Version	Changes
21-May-2024	1	Initial release
22-Apr-2025	2	Updated cover image. Updated images in Table 1. Evaluation & development setup with CAM-66GY promodules. Table 2. Technical specifications: Updated depth of field values.

IMPORTANT NOTICE – READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgment.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, refer to www.st.com/trademarks. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2025 STMicroelectronics – All rights reserved